



**NEXCOM International Co., Ltd.**

**Intelligent Platform & Services Business Group**

**COM Express Type 6**

**ICES 675**

User Manual

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# PREFACE

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## Disclaimer

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## Acknowledgements

ICES 675 is a trademark of NEXCOM International Co., Ltd. All other product names mentioned herein are registered trademarks of their respective owners.

## Regulatory Compliance Statements

This section provides the FCC compliance statement for Class B devices and describes how to keep the system CE compliant.

## Declaration of Conformity

### FCC

This equipment has been tested and verified to comply with the limits for a Class B digital device, pursuant to Part 15 of FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. Operation of this equipment in a residential area (domestic environment) is likely to cause harmful interference, in which case the user will be required to correct the interference (take adequate measures) at their own expense.

### CE

The product(s) described in this manual complies with all applicable European Union (CE) directives if it has a CE marking. For computer systems to remain CE compliant, only CE-compliant parts may be used. Maintaining CE compliance also requires proper cable and cabling techniques.

## RoHS Compliance



### **NEXCOM RoHS Environmental Policy and Status Update**

NEXCOM is a global citizen for building the digital infrastructure. We are committed to providing green products and services, which are compliant with European Union RoHS (Restriction on Use of Hazardous Substance in Electronic Equipment) directive 2011/65/EU, to be your trusted green partner and to protect our environment.

RoHS restricts the use of Lead (Pb) < 0.1% or 1,000ppm, Mercury (Hg) < 0.1% or 1,000ppm, Cadmium (Cd) < 0.01% or 100ppm, Hexavalent Chromium (Cr6+) < 0.1% or 1,000ppm, Polybrominated biphenyls (PBB) < 0.1% or 1,000ppm, and Polybrominated diphenyl Ethers (PBDE) < 0.1% or 1,000ppm.

In order to meet the RoHS compliant directives, NEXCOM has established an engineering and manufacturing task force to implement the introduction of green products. The task force will ensure that we follow the standard NEXCOM development procedure and that all the new RoHS components and new manufacturing processes maintain the highest industry quality levels for which NEXCOM are renowned.

The model selection criteria will be based on market demand. Vendors and suppliers will ensure that all designed components will be RoHS compliant.

### **How to recognize NEXCOM RoHS Products?**

For existing products where there are non-RoHS and RoHS versions, the suffix "(LF)" will be added to the compliant product name.

All new product models launched after January 2013 will be RoHS compliant. They will use the usual NEXCOM naming convention.

## Warranty and RMA

### NEXCOM Warranty Period

NEXCOM manufactures products that are new or equivalent to new in accordance with industry standard. NEXCOM warrants that products will be free from defect in material and workmanship for 2 years, beginning on the date of invoice by NEXCOM. HCP series products (Blade Server) which are manufactured by NEXCOM are covered by a three year warranty period.

### NEXCOM Return Merchandise Authorization (RMA)

- Customers shall enclose the “NEXCOM RMA Service Form” with the returned packages.
- Customers must collect all the information about the problems encountered and note anything abnormal or, print out any on-screen messages, and describe the problems on the “NEXCOM RMA Service Form” for the RMA number apply process.
- Customers can send back the faulty products with or without accessories (manuals, cable, etc.) and any components from the card, such as CPU and RAM. If the components were suspected as part of the problems, please note clearly which components are included. Otherwise, NEXCOM is not responsible for the devices/parts.
- Customers are responsible for the safe packaging of defective products, making sure it is durable enough to be resistant against further damage and deterioration during transportation. In case of damages occurred during transportation, the repair is treated as “Out of Warranty.”
- Any products returned by NEXCOM to other locations besides the customers’ site will bear an extra charge and will be billed to the customer.

### Repair Service Charges for Out-of-Warranty Products

NEXCOM will charge for out-of-warranty products in two categories, one is basic diagnostic fee and another is component (product) fee.

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NEXCOM will charge for out-of-warranty products in two categories, one is basic diagnostic fee and another is component (product) fee.

### System Level

- Component fee: NEXCOM will only charge for main components such as SMD chip, BGA chip, etc. Passive components will be repaired for free, ex: resistor, capacitor.
- Items will be replaced with NEXCOM products if the original one cannot be repaired. Ex: motherboard, power supply, etc.
- Replace with 3rd party products if needed.
- If RMA goods can not be repaired, NEXCOM will return it to the customer without any charge.

### Board Level

- Component fee: NEXCOM will only charge for main components, such as SMD chip, BGA chip, etc. Passive components will be repaired for free, ex: resistors, capacitors.
- If RMA goods can not be repaired, NEXCOM will return it to the customer without any charge.

## Warnings

Read and adhere to all warnings, cautions, and notices in this guide and the documentation supplied with the chassis, power supply, and accessory modules. If the instructions for the chassis and power supply are inconsistent with these instructions or the instructions for accessory modules, contact the supplier to find out how you can ensure that your computer meets safety and regulatory requirements.

## Cautions

Electrostatic discharge (ESD) can damage system components. Do the described procedures only at an ESD workstation. If no such station is available, you can provide some ESD protection by wearing an antistatic wrist strap and attaching it to a metal part of the computer chassis.

## Safety Information

Before installing and using the device, note the following precautions:

- Read all instructions carefully.
- Do not place the unit on an unstable surface, cart, or stand.
- Follow all warnings and cautions in this manual.
- When replacing parts, ensure that your service technician uses parts specified by the manufacturer.
- Avoid using the system near water, in direct sunlight, or near a heating device.
- The load of the system unit does not solely rely for support from the rackmounts located on the sides. Firm support from the bottom is highly necessary in order to provide balance stability.

## Installation Recommendations

Ensure you have a stable, clean working environment. Dust and dirt can get into components and cause a malfunction. Use containers to keep small components separated.

Adequate lighting and proper tools can prevent you from accidentally damaging the internal components. Most of the procedures that follow require only a few simple tools, including the following:

- A Philips screwdriver
- A flat-tipped screwdriver
- A grounding strap
- An anti-static pad

Using your fingers can disconnect most of the connections. It is recommended that you do not use needle-nose pliers to disconnect connections as these can damage the soft metal or plastic parts of the connectors.

## Safety Precautions

1. Read these safety instructions carefully.
2. Keep this User Manual for later reference.
3. Disconnect the equipment from any AC outlet before cleaning or installing a component inside the chassis. Use a damp cloth. Do not use liquid or spray detergents for cleaning.
4. To prevent electrostatic build-up, leave the board in its anti-static bag until you are ready to install it.
5. For plug-in equipment, the power outlet socket must be located near the equipment and must be easily accessible.
6. Keep the board away from humidity.
7. Put the board on a stable surface. Dropping it or letting it fall may cause damage.
8. Wear anti-static wrist strap.
9. Do all preparation work on a static-free surface.
10. Make sure the voltage of the power source is correct before connecting the equipment to the power outlet.
11. Hold the board only by its edges. Be careful not to touch any of the components, contacts or connections.
12. All cautions and warnings on the board should be noted.
13. Use the correct mounting screws and do not over tighten the screws.
14. Keep the original packaging and the anti-static bag; in case the board has to be returned for repair or replacement.



## Technical Support and Assistance

1. For the most updated information of NEXCOM products, visit NEXCOM's website at [www.nexcom.com](http://www.nexcom.com).
2. For technical issues that require contacting our technical support team or sales representative, please have the following information ready before calling:
  - Product name and serial number
  - Detailed information of the peripheral devices
  - Detailed information of the installed software (operating system, version, application software, etc.)
  - A complete description of the problem
  - The exact wordings of the error messages

### Warning!

1. Handling the unit: carry the unit with both hands and handle it with care.
2. Maintenance: to keep the unit clean, use only approved cleaning products or clean with a dry cloth.

## Conventions Used in this Manual



### Warning:

Information about certain situations, which if not observed, can cause personal injury. This will prevent injury to yourself when performing a task.



### Caution:

Information to avoid damaging components or losing data.



### Note:

Provides additional information to complete a task easily.

## Global Service Contact Information

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## Package Contents

Before continuing, verify that the ICES 675 package that you received is complete. Your package should have the item listed in the table below. The CPU fan kit, heat spreader kit and carrier board are optional accessories.

Item	Description	Qty
1	ICES 675 Mainboard	1

### CPU Fan, Heat Spreader and Carrier Board (Optional)

Item	Part Number	Description
1	TBD	ICES 675 Heat Spreader Kit
2	TBD	ICES 675 CPU Cooler Kit
3	10KB0806000X0	ICEB 8060 (COM Express Carrier Board)



#### Heat Spreader:

Please note that the heat spreader is a thermal coupling device that comes in contact with the CPU through thermal gap fillers. It is designed to transfer the heat away from the CPU and is different to a heatsink in terms of cooling properties. Please do not consider it as a heatsink.

Additional thermal gap fillers can be used on other components on the module to allow them to come in contact with the heat spreader for heat dissipation.

## Ordering Information

The following information below provides ordering information for ICES 675.

### **ICES 675 (P/N: 10K00067500X0)**

Onboard 8th generation Intel® Xeon® E-2176M processor, 2 x DDR4 SO-DIMM (support ECC), support multiple displays via VGA/LVDS/DDI1/2, 4 x SATAIII, 1 x GbE LAN, 2 x COM, 4 x USB 3.0, 8 x USB 2.0, HD audio, 8-bit GPIO

### **ICES 675 (P/N: TBD)**

Onboard 8th generation Intel® Core™ i7-8850H processor, 2 x DDR4 SO-DIMM (non-ECC), support multiple displays via VGA/LVDS/DDI1/2, 4 x SATAIII, 1 x GbE LAN, 2 x COM, 4 x USB 3.0, 8 x USB 2.0, HD audio, 8-bit GPIO

### **ICES 675 (P/N: TBD)**

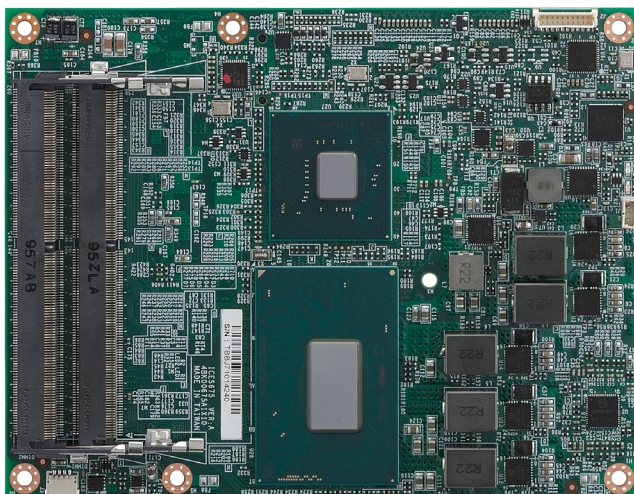
Onboard 8th generation Intel® Core™ i5-8400H processor, 2 x DDR4 SO-DIMM (non-ECC), support multiple displays via VGA/LVDS/DDI1/2, 4 x SATAIII, 1 x GbE LAN, 2 x COM, 4 x USB 3.0, 8 x USB 2.0, HD audio, 8-bit GPIO

### **Optional Accessories**

- **CPU Cooler (P/N: TBD)**
- **Heat Spreader (P/N: TBD)**
- **TPM 2.0 Module Kit (P/N: 79E00TPM01X00)**

# CHAPTER 1: PRODUCT INTRODUCTION

## Overview - ICES 675



## Key Features

- 8th generation Intel® Core™ processors, BGA 1440, PCH CM246
- 2 channel DDR4 with ECC or non-ECC SO-DIMM 2666MHz up to 32GB
- Support triple display VGA, 2 x DP, eDP/LVDS 24-bit dual channel
- PCI Express lane x16 (configurable: "1 x 16", "2 x 8", "1 x 8 + 2 x 4")
- PCI Express lane x1 (Gen 3), 8 x (can be configured to "x 1", "x 4")
- IO: 2 x UART (RX/TX), 8-bit DIO, WDT, TPM (optional)

## Hardware Specifications

### CPU/Chipset

- 8th generation Intel® Core™ processors, BGA 1440
- Intel® Xeon® E-2176M processor, 6 Cores, 12M Cache, 2.7GHz (4.4GHz), 45W (support ECC)
- Intel® Core™ i7-8850H processor, 6 Cores, 12M Cache, 2.6GHz (4.3GHz), 45W
- Intel® Core™ i5-8400H processor, 4 cores, 8M Cache, 2.5GHz (4.2GHz), 45W
- Intel® Mobile CM246

### Main Memory

- Dual channel DDR4 SO-DIMM memory socket with non-ECC support, up to 32 GB 2666MHz, optional ECC support with Intel® Xeon® E-2176M processor

### Display

- Integrated Intel® Gen9 graphics graphic engine
- 1 x VGA connector (resolution up to 1920x1080 @ 60Hz)
- 1 x LVDS connector (resolution up to 1920x1080 @ 60Hz)
- DDI 1/2 port configurable to HDMI 1.4/DVI/DisplayPort 1.4 HDMI up to 4096x2160 @ 30Hz/24bpp, DVI up to 1920x1200 @60Hz, DP up to 4096x2304 @ 60Hz

### BIOS

- AMI (UEFI)

### COM Express Connector

- AB  
LVDS: (LVDS/eDP co-lay), VGA: (VGA/DDI port3 co-lay), 1 x GbE LAN, 6 x PCIe x1, HD Audio, 4 x SATA III, 8 x USB 2.0, LPC Bus, SMBus/I2C, 2 x COM, GPIO 8-bit
- CD  
DDI1, DDI2, 1 x PCIe x16, 2 x PCIe x1, 4 x USB 3.0

### Power Requirements

- +12VDC, +5Vsb
- Support both AT and ATX power supply mode

### Dimensions

- 125mm (W) x 95mm (L)

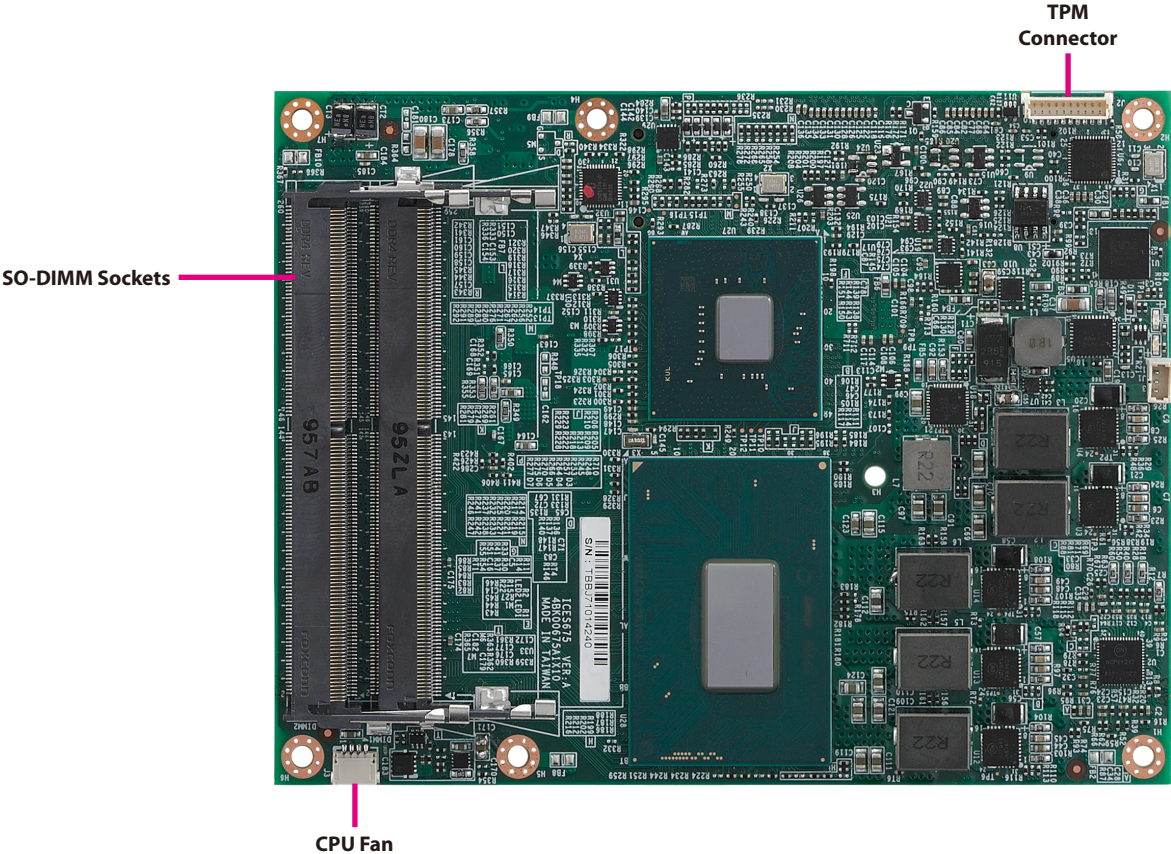
### Environment

- Board level operating temperatures: 0°C to 60°C
- Storage temperatures: -20°C to 85°C
- Relative humidity:  
10% to 95% (operating, non-condensing)  
5% to 95% (non-operating, non-condensing)

### Certifications

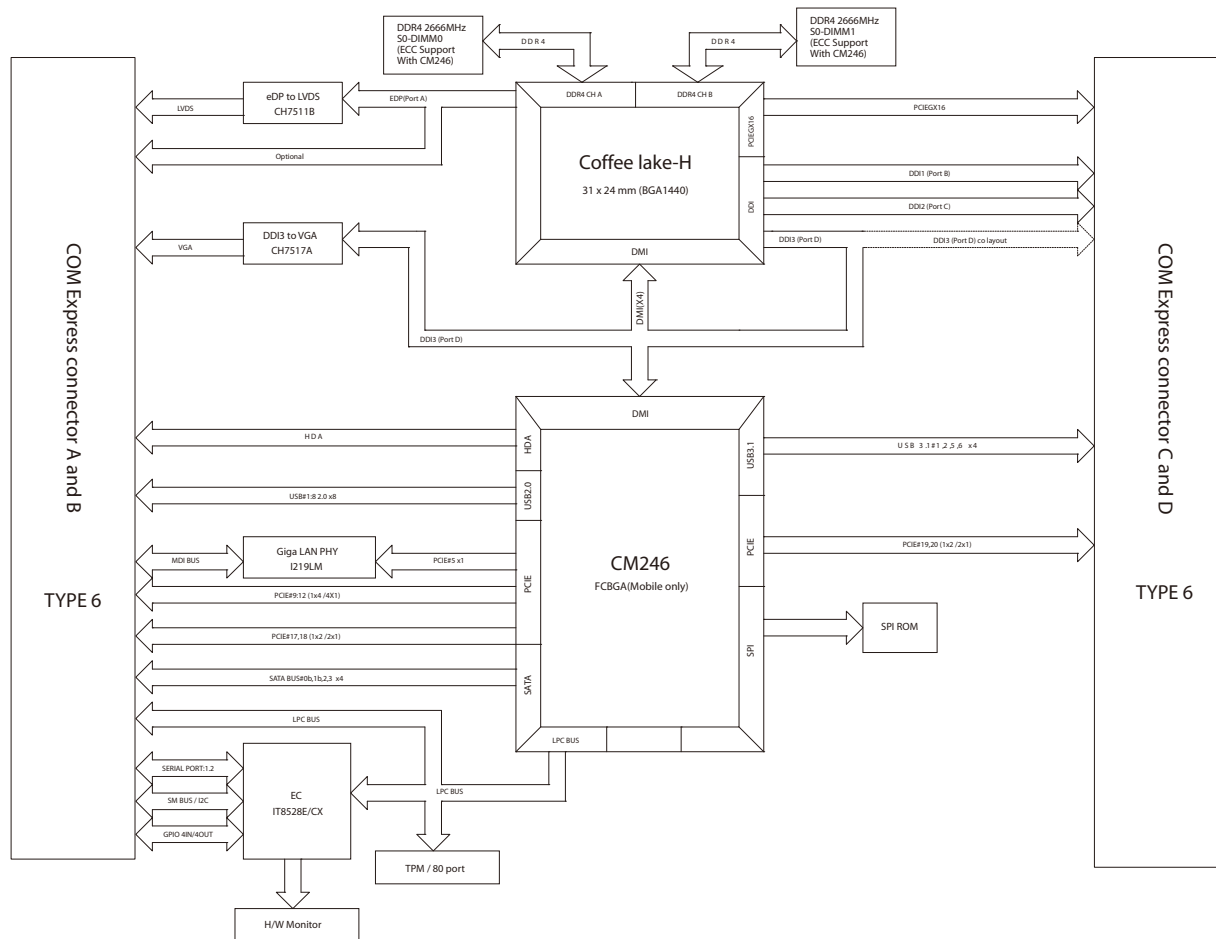
- Meet CE/FCC Class B

# Knowing Your ICES 675





## Block Diagram



## CHAPTER 2: CONNECTOR PINOUT ASSIGNMENTS

### Before You Begin

- Ensure you have a stable, clean working environment. Dust and dirt can get into components and cause a malfunction. Use containers to keep small components separated.
- Adequate lighting and proper tools can prevent you from accidentally damaging the internal components. Most of the procedures that follow require only a few simple tools, including the following:
  - A Philips screwdriver
  - A flat-tipped screwdriver
  - A set of jewelers screwdrivers
  - A grounding strap
  - An anti-static pad
- Using your fingers can disconnect most of the connections. It is recommended that you do not use needle-nosed pliers to disconnect connections as these can damage the soft metal or plastic parts of the connectors.
- Before working on internal components, make sure that the power is off. Ground yourself before touching any internal components, by touching a metal object. Static electricity can damage many of the electronic components. Humid environments tend to have less static electricity than dry environments. A grounding strap is warranted whenever danger of static electricity exists.

### Precautions

Computer components and electronic circuit boards can be damaged by discharges of static electricity. Working on computers that are still connected to a power supply can be extremely dangerous.

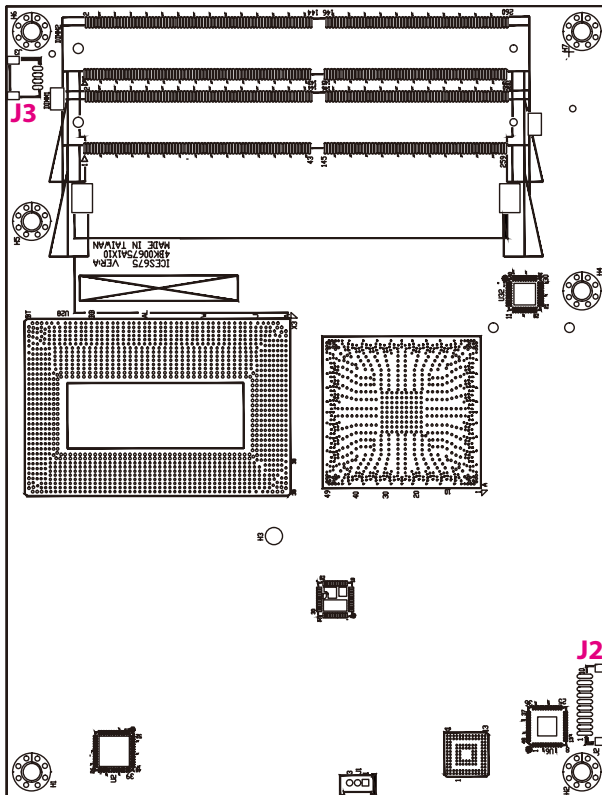
Follow the guidelines below to avoid damage to your computer or yourself:

- Always disconnect the unit from the power outlet whenever you are working inside the case.
- If possible, wear a grounded wrist strap when you are working inside the computer case. Alternatively, discharge any static electricity by touching the bare metal chassis of the unit case, or the bare metal body of any other grounded appliance.
- Hold electronic circuit boards by the edges only. Do not touch the components on the board unless it is necessary to do so. Don't flex or stress the circuit board.
- Leave all components inside the static-proof packaging that they shipped with until they are ready for installation.
- Use correct screws and do not over tighten screws.

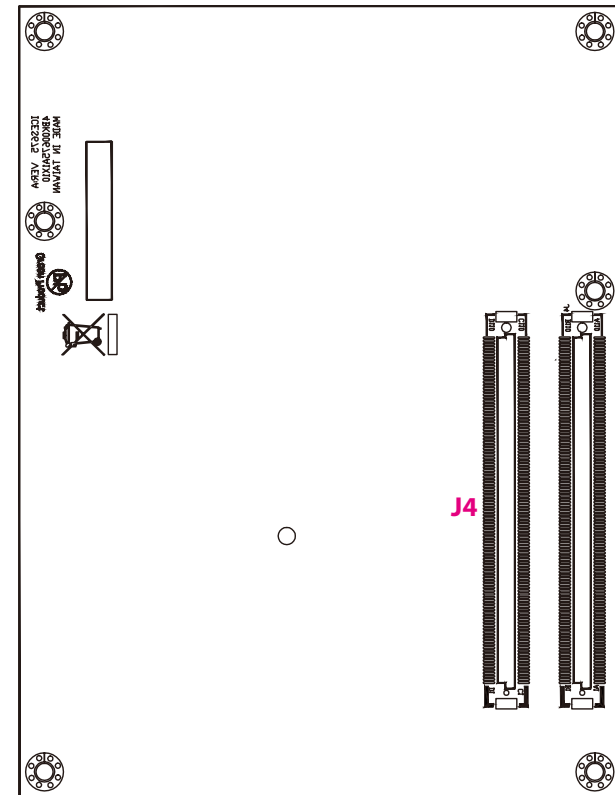
## Locations of the Connectors

The figures below show the locations of the connectors for ICES 675.

### Top View



### Bottom View

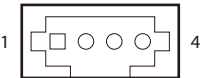


# Connector Pin Definitions

## Internal Connectors

### CPU Fan

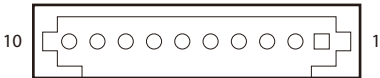
Connector type: 1x4 4-pin header  
Connector location: J3



Pin	Definition	Pin	Definition
1	PWM	2	TACH
3	+12V	4	GND

### TPM Connector

Connector type: 1x10 10-pin header  
Connector location: J2



Pin	Definition	Pin	Definition
1	GND	2	I_PLTRST#
3	CLKOUT_LPC1	4	LPC_FRAME#
5	LAD3	6	LAD2
7	LAD1	8	LAD0
9	LPC_SERIRQ_C	10	+3V3

## High Speed Board-to-Board Connector: Row A and B, Row C and D

Connector location: J4



Pin	Definition	Pin	Definition	Pin	Definition	Pin	Definition
A1	GND(FIXED)	B1	GND(FIXED)	C1	GND(FIXED)	D1	GND(FIXED)
A2	GBE0_MDI3-	B2	GBE0_ACT#	C2	GND	D2	GND
A3	GBE0_MDI3+	B3	LPC_FRAME#	C3	USB_SSRX0-	D3	USB_SSTX0-
A4	GBE0_LINK100#	B4	LPC_AD0	C4	USB_SSRX0+	D4	USB_SSTX0+
A5	GBE0_LINK1000#	B5	LPC_AD1	C5	GND	D5	GND
A6	GBE0_MDI2-	B6	LPC_AD2	C6	USB_SSRX1-	D6	USB_SSTX1-
A7	GBE0_MDI2+	B7	LPC_AD3	C7	USB_SSRX1+	D7	USB_SSTX1+
A8	GBE0_LINK#	B8	LPC_DRQ0#	C8	GND	D8	GND
A9	GBE0_MDI1-	B9	LPC_DRQ1#	C9	USB_SSRX2-	D9	USB_SSTX2-
A10	GBE0_MDI1+	B10	LPC_CLK	C10	USB_SSRX2+	D10	USB_SSTX2+
A11	GND(FIXED)	B11	GND(FIXED)	C11	GND(FIXED)	D11	GND(FIXED)
A12	GBE0_MDI0-	B12	PWRBTN#	C12	USB_SSRX3-	D12	USB_SSTX3-
A13	GBE0_MDI0+	B13	SMB_CK	C13	USB_SSRX3+	D13	USB_SSTX3+

Pin	Definition	Pin	Definition	Pin	Definition	Pin	Definition
A14	GBE0_CTREF	B14	SMB_DAT	C14	GND	D14	GND
A15	SUS_S3#	B15	SMB_ALERT#	C15	NC	D15	DDI1_CTRL_CLK_AUX+
A16	SATA0_TX+	B16	SATA1_TX+	C16	NC	D16	DDI1_CTRL_DATA_AUX-
A17	SATA0_TX-	B17	SATA1_TX-	C17	RSVD	D17	RSVD
A18	SUS_S4#	B18	SUS_STAT#	C18	RSVD	D18	RSVD
A19	SATA0_RX+	B19	SATA1_RX+	C19	PCIE_RX6+	D19	PCIE_TX6+
A20	SATA0_RX-	B20	SATA1_RX-	C20	PCIE_RX6-	D20	PCIE_TX6-
A21	GND(FIXED)	B21	GND(FIXED)	C21	GND(FIXED)	D21	GND(FIXED)
A22	SATA2_TX+	B22	SATA3_TX+	C22	NC	D22	NC
A23	SATA2_TX-	B23	SATA3_TX-	C23	NC	D23	NC
A24	SUS_S5#	B24	PWR_OK	C24	DDI1_HPD	D24	RSVD
A25	SATA2_RX+	B25	SATA3_RX+	C25	NC	D25	RSVD
A26	SATA2_RX-	B26	SATA3_RX-	C26	NC	D26	DDI1_PAIR0+
A27	BATLOW#	B27	WDT	C27	RSVD	D27	DDI1_PAIR0-
A28	(S)ATA_ACT#	B28	AC/HDA_SDIN2	C28	RSVD	D28	RSVD
A29	AC/HDA_SYNC	B29	AC/HDA_SDIN1	C29	NC	D29	DDI1_PAIR1+
A30	AC/HDA_RST#	B30	AC/HDA_SDINO	C30	NC	D30	DDI1_PAIR1-
A31	GND(FIXED)	B31	GND(FIXED)	C31	GND(FIXED)	D31	GND(FIXED)
A32	AC/HDA_BITCLK	B32	SPKR	C32	DDI2_CTRL_CLK_AUX+	D32	DDI1_PAIR2+
A33	AC/HDA_SDOUT	B33	I2C_CK	C33	DDI2_CTRL_DATA_AUX-	D33	DDI1_PAIR2-
A34	BIOS_DIS0#	B34	I2C_DAT	C34	DDI2_DDC_AUX_SEL	D34	DDI1_DDC_AUX_SEL
A35	THRMTRIP#	B35	THRM#	C35	RSVD	D35	RSVD
A36	USB6-	B36	USB7-	C36	DDI3_CTRL_CLK_AUX+	D36	DDI1_PAIR3+
A37	USB6+	B37	USB7+	C37	DDI3_CTRL_DATA_AUX-	D37	DDI1_PAIR3-
A38	USB_6_7_OC#	B38	USB_4_5_OC#	C38	DDI3_DDC_AUX_SEL	D38	RSVD
A39	USB4-	B39	USB5-	C39	DDI3_PAIR0+	D39	DDI2_PAIR0+
A40	USB4+	B40	USB5+	C40	DDI3_PAIR0-	D40	DDI2_PAIR0-
A41	GND(FIXED)	B41	GND(FIXED)	C41	GND(FIXED)	D41	GND(FIXED)

Pin	Definition	Pin	Definition	Pin	Definition	Pin	Definition
A42	USB2-	B42	USB3-	C42	DDI3_PAIR1+	D42	DDI2_PAIR1+
A43	USB2+	B43	USB3+	C43	DDI3_PAIR1-	D43	DDI2_PAIR1-
A44	USB_2_3_OC#	B44	USB_0_1_OC#	C44	DDI3_HPD	D44	DDI2_HPD
A45	USB0-	B45	USB1-	C45	RSVD	D45	RSVD
A46	USB0+	B46	USB1+	C46	DDI3_PAIR2+	D46	DDI2_PAIR2+
A47	VCC_RTC	B47	EXCD1_PERST#	C47	DDI3_PAIR2-	D47	DDI2_PAIR2-
A48	EXCD0_PERST#	B48	NC	C48	RSVD	D48	RSVD
A49	NC	B49	SYS_RESET#	C49	DDI3_PAIR3+	D49	DDI2_PAIR3+
A50	LPC_SERIRQ	B50	CB_RESET#	C50	DDI3_PAIR3-	D50	DDI2_PAIR3-
A51	GND(FIXED)	B51	GND(FIXED)	C51	GND(FIXED)	D51	GND(FIXED)
A52	PCIE_TX5+	B52	PCIE_RX5+	C52	PEG_RX0+	D52	PEG_TX0+
A53	PCIE_TX5-	B53	PCIE_RX5-	C53	PEG_RX0-	D53	PEG_TX0-
A54	GPIO	B54	GPO1	C54	TYPE0#	D54	COM_CFG2
A55	PCIE_TX4+	B55	PCIE_RX4+	C55	PEG_RX1+	D55	PEG_TX1+
A56	PCIE_TX4-	B56	PCIE_RX4-	C56	PEG_RX1-	D56	PEG_TX1-
A57	GND	B57	GPO2	C57	TYPE1#	D57	TYPE2#
A58	PCIE_TX3+	B58	PCIE_RX3+	C58	PEG_RX2+	D58	PEG_TX2+
A59	PCIE_TX3-	B59	PCIE_RX3-	C59	PEG_RX2-	D59	PEG_TX2-
A60	GND(FIXED)	B60	GND(FIXED)	C60	GND(FIXED)	D60	GND(FIXED)
A61	PCIE_TX2+	B61	PCIE_RX2+	C61	PEG_RX3+	D61	PEG_TX3+
A62	PCIE_TX2-	B62	PCIE_RX2-	C62	PEG_RX3-	D62	PEG_TX3-
A63	GPI1	B63	GPO3	C63	RSVD	D63	RSVD
A64	PCIE_TX1+	B64	PCIE_RX1+	C64	RSVD	D64	RSVD
A65	PCIE_TX1-	B65	PCIE_RX1-	C65	PEG_RX4+	D65	PEG_TX4+
A66	GND	B66	WAKE0#	C66	PEG_RX4-	D66	PEG_TX4-
A67	GPI2	B67	WAKE1#	C67	RSVD	D67	GND
A68	PCIE_TX0+	B68	PCIE_RX0+	C68	PEG_RX5+	D68	PEG_TX5+
A69	PCIE_TX0-	B69	PCIE_RX0-	C69	PEG_RX5-	D69	PEG_TX5-

Pin	Definition	Pin	Definition	Pin	Definition	Pin	Definition
A70	GND(FIXED)	B70	GND(FIXED)	C70	GND(FIXED)	D70	GND(FIXED)
A71	LVDS_A0+	B71	LVDS_B0+	C71	PEG_RX6+	D71	PEG_TX6+
A72	LVDS_A0-	B72	LVDS_B0-	C72	PEG_RX6-	D72	PEG_TX6-
A73	LVDS_A1+	B73	LVDS_B1+	C73	GND	D73	GND
A74	LVDS_A1-	B74	LVDS_B1-	C74	PEG_RX7+	D74	PEG_TX7+
A75	LVDS_A2+	B75	LVDS_B2+	C75	PEG_RX7-	D75	PEG_TX7-
A76	LVDS_A2-	B76	LVDS_B2-	C76	GND	D76	GND
A77	LVDS_VDD_EN	B77	LVDS_B3+	C77	RSVD	D77	RSVD
A78	LVDS_A3+	B78	LVDS_B3-	C78	PEG_RX8+	D78	PEG_TX8+
A79	LVDS_A3-	B79	LVDS_BKLT_EN	C79	PEG_RX8-	D79	PEG_TX8-
A80	GND(FIXED)	B80	GND(FIXED)	C80	GND(FIXED)	D80	GND(FIXED)
A81	LVDS_A_CK+	B81	LVDS_B_CK+	C81	PEG_RX9+	D81	PEG_TX9+
A82	LVDS_A_CK-	B82	LVDS_B_CK-	C82	PEG_RX9-	D82	PEG_TX9-
A83	LVDS_I2C_CK	B83	LVDS_BKLT_CTRL	C83	RSVD	D83	RSVD
A84	LVDS_I2C_DAT	B84	VCC_5V_SBY	C84	GND	D84	GND
A85	GPI3	B85	VCC_5V_SBY	C85	PEG_RX10+	D85	PEG_TX10+
A86	RSVD	B86	VCC_5V_SBY	C86	PEG_RX10-	D86	PEG_TX10-
A87	EDP_HPD	B87	VCC_5V_SBY	C87	GND	D87	GND
A88	PCIE_CLK_REF+	B88	BIOS_DIS1#	C88	PEG_RX11+	D88	PEG_TX11+
A89	PCIE_CLK_REF-	B89	VGA_RED	C89	PEG_RX11-	D89	PEG_TX11-
A90	GND(FIXED)	B90	GND(FIXED)	C90	GND(FIXED)	D90	GND(FIXED)
A91	SPI_POWER	B91	VGA_GRN	C91	PEG_RX12+	D91	PEG_TX12+
A92	SPI_MISO	B92	VGA_BLUE	C92	PEG_RX12-	D92	PEG_TX12-
A93	GPO0	B93	VGA_HSYNC	C93	GND	D93	GND
A94	SPI_CLK	B94	VGA_VSYNC	C94	PEG_RX13+	D94	PEG_TX13+
A95	SPI_MOSI	B95	VGA_I2C_CK	C95	PEG_RX13-	D95	PEG_TX13-
A96	TPM_PP	B96	VGA_I2C_DAT	C96	GND	D96	GND
A97	TYPE10#	B97	SPI_CS#	C97	RSVD	D97	RSVD



Pin	Definition	Pin	Definition	Pin	Definition	Pin	Definition
A98	SERO_TX	B98	RSVD	C98	PEG_RX14+	D98	PEG_TX14+
A99	SERO_RX	B99	RSVD	C99	PEG_RX14-	D99	PEG_TX14-
A100	GND(FIXED)	B100	GND(FIXED)	C100	GND(FIXED)	D100	GND(FIXED)
A101	SER1_TX	B101	FAN_PWMOUT	C101	PEG_RX15+	D101	PEG_TX15+
A102	SER1_RX	B102	FAN_TACHIN	C102	PEG_RX15-	D102	PEG_TX15-
A103	NC	B103	NC	C103	GND	D103	GND
A104	VCC_12V	B104	VCC_12V	C104	VCC_12V	D104	VCC_12V
A105	VCC_12V	B105	VCC_12V	C105	VCC_12V	D105	VCC_12V
A106	VCC_12V	B106	VCC_12V	C106	VCC_12V	D106	VCC_12V
A107	VCC_12V	B107	VCC_12V	C107	VCC_12V	D107	VCC_12V
A108	VCC_12V	B108	VCC_12V	C108	VCC_12V	D108	VCC_12V
A109	VCC_12V	B109	VCC_12V	C109	VCC_12V	D109	VCC_12V
A110	GND(FIXED)	B110	GND(FIXED)	C110	GND(FIXED)	D110	GND(FIXED)

# CHAPTER 3: BIOS SETUP

This chapter describes how to use the BIOS setup program for ICES 675. The BIOS screens provided in this chapter are for reference only and may change if the BIOS is updated in the future.

To check for the latest updates and revisions, visit the NEXCOM website at [www.nexcom.com.tw](http://www.nexcom.com.tw).

## About BIOS Setup

The BIOS (Basic Input and Output System) Setup program is a menu driven utility that enables you to make changes to the system configuration and tailor your system to suit your individual work needs. It is a ROM-based configuration utility that displays the system's configuration status and provides you with a tool to set system parameters.

These parameters are stored in non-volatile battery-backed-up CMOS RAM that saves this information even when the power is turned off. When the system is turned back on, the system is configured with the values found in CMOS.

With easy-to-use pull down menus, you can configure such items as:

- Hard drives, diskette drives, and peripherals
- Video display type and display options
- Password protection from unauthorized use
- Power management features

The settings made in the setup program affect how the computer performs. It is important, therefore, first to try to understand all the setup options, and second, to make settings appropriate for the way you use the computer.

## When to Configure the BIOS

- This program should be executed under the following conditions:
- When changing the system configuration
- When a configuration error is detected by the system and you are prompted to make changes to the setup program
- When resetting the system clock
- When redefining the communication ports to prevent any conflicts
- When making changes to the Power Management configuration
- When changing the password or making other changes to the security setup

Normally, CMOS setup is needed when the system hardware is not consistent with the information contained in the CMOS RAM, whenever the CMOS RAM has lost power, or the system features need to be changed.

## Default Configuration

Most of the configuration settings are either predefined according to the Load Optimal Defaults settings which are stored in the BIOS or are automatically detected and configured without requiring any actions. There are a few settings that you may need to change depending on your system configuration.

## Entering Setup














When the system is powered on, the BIOS will enter the Power-On Self Test (POST) routines. These routines perform various diagnostic checks; if an error is encountered, the error will be reported in one of two different ways:

- If the error occurs before the display device is initialized, a series of beeps will be transmitted.
- If the error occurs after the display device is initialized, the screen will display the error message.

Powering on the computer and immediately pressing <Del> allows you to enter Setup.

Press the  key to enter Setup:


## Legends

Key	Function
 	Moves the highlight left or right to select a menu.
 	Moves the highlight up or down between sub-menus or fields.
	Exits the BIOS Setup Utility.
	Scrolls forward through the values or options of the highlighted field.
	Scrolls backward through the values or options of the highlighted field.
	Selects a field.
	Displays General Help.
	Load previous values.
	Load optimized default values.
	Saves and exits the Setup program.
	Press <Enter> to enter the highlighted sub-menu.


## Scroll Bar

When a scroll bar appears to the right of the setup screen, it indicates that there are more available fields not shown on the screen. Use the up and down arrow keys to scroll through all the available fields.

## Submenu

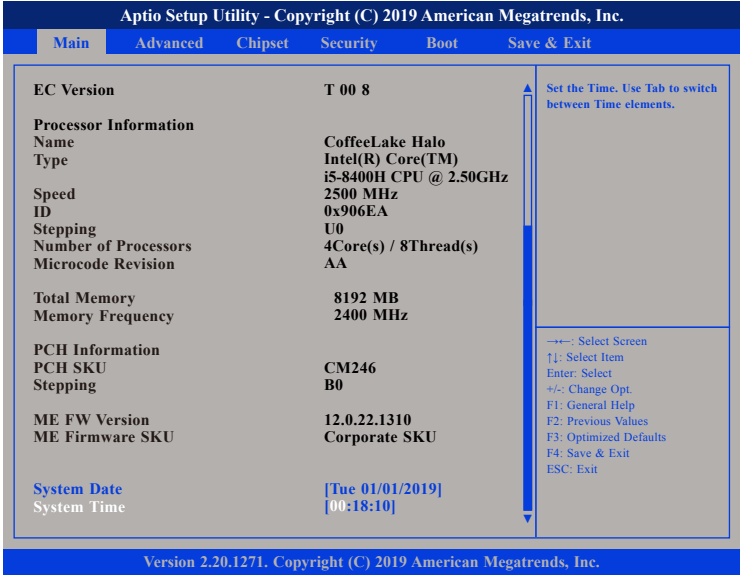
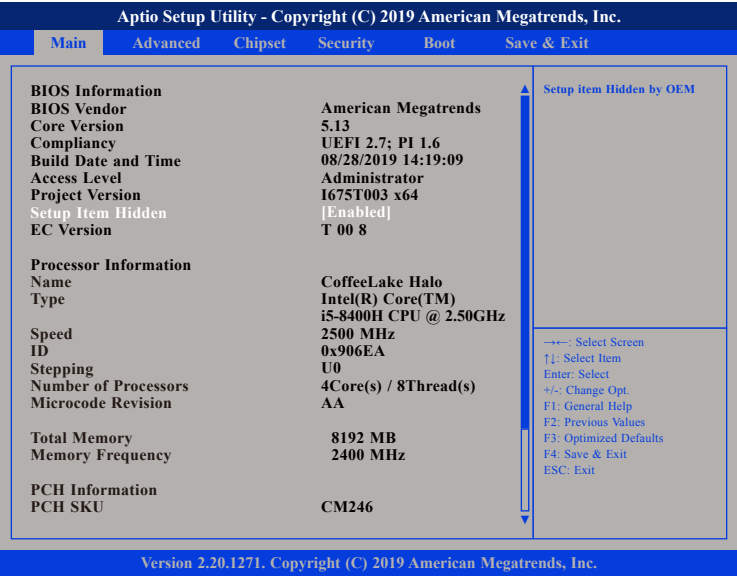
When “▶” appears on the left of a particular field, it indicates that a submenu which contains additional options are available for that field. To display the submenu, move the highlight to that field and press  .

# BIOS Setup Utility

Once you enter the AMI BIOS Setup Utility, the Main Menu will appear on the screen. The main menu allows you to select from several setup functions and one exit. Use arrow keys to select among the items and press  to accept or enter the submenu.

## Main

The Main menu is the first screen that you will see when you enter the BIOS Setup Utility.



## Setup Item Hidden

Enables or disables hidden setup items.

## System Date

The date format is <day>, <month>, <date>, <year>. Day displays a day, from Monday to Sunday. Month displays the month, from January to December. Date displays the date, from 1 to 31. Year displays the year, from 1999 to 2099.

## System Time

The time format is <hour>, <minute>, <second>. The time is based on the 24-hour military-time clock. For example, 1 p.m. is 13:00:00. Hour displays hours from 00 to 23. Minute displays minutes from 00 to 59. Second displays seconds from 00 to 59.



## Advanced

The Advanced menu allows you to configure your system for basic operation. Some entries are defaults required by the system board, while others, if enabled, will improve the performance of your system or let you set some features according to your preference.



Setting incorrect field values may cause the system to malfunction.



## RC ACPI Settings

This section is used to configure ACPI settings.



### Enable Hibernation

Enables or disables system ability to hibernate (OS/S4 Sleep State). This option may not be effective with some OS.

### ACPI Sleep State

Select the highest ACPI sleep state the system will enter when the suspend button is pressed. The options are Suspend Disabled and S3 (Suspend to RAM).



### CPU Configuration

This section is used to configure the CPU.

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Advanced

CPU Configuration

Type

Intel(R) Core(TM)

i5-8400H CPU @ 2.50GHz

ID

0x906EA

Speed

2500 MHz

L1 Data Cache

32 KB x 4

L1 Instruction Cache

32 KB x 4

L2 Cache

256 KB x 4

L3 Cache

8 MB

L4 Cache

N/A

VMX

Supported

SMX/TXT

Supported

Intel (VMX) Virtualization Technology

[Enabled]

Active Processor Cores

[All]

Hyper-Threading

[Enabled]

When enabled, a VMM can utilize the additional hardware capabilities provided by Vanderpool Technology.

→←: Select Screen

↑↓: Select Item

Enter: Select

+/-: Change Opt.

F1: General Help

F2: Previous Values

F3: Optimized Defaults

F4: Save & Exit

ESC: Exit

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#### Intel® (VMX) Virtualization Technology

Enables or disables Intel Virtualization technology. When enabled, a VMM can utilize the additional hardware capabilities provided by Vanderpool Technology.

#### Active Processor Cores

Select the number of cores to enable in each processor package.

#### Hyper-Threading

Enables or disables Hyper-Threading technology.

### Power & Performance

This section is used to configure the CPU power management features.

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Advanced

Power & Performance

▶ CPU - Power Management Control

CPU - Power Management Control Options

→←: Select Screen

↑↓: Select Item

Enter: Select

+/-: Change Opt.

F1: General Help

F2: Previous Values

F3: Optimized Defaults

F4: Save & Exit

ESC: Exit

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#### CPU - Power Management Control

Enters the CPU - Power Management Control submenu.





CPU - Power Management Control

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Advanced

CPU - Power Management Control

Intel(R) SpeedStep(tm)

[Enabled]

Turbo Mode

[Enabled]

C states

[Enabled]

Allows more than two frequency ranges to be supported.

→←: Select Screen

↑↓: Select Item

Enter: Select

+/-: Change Opt.

F1: General Help

F2: Previous Values

F3: Optimized Defaults

F4: Save & Exit

ESC: Exit

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- Intel® SpeedStep™**  
Enables or disables Intel SpeedStep.
- Turbo Mode**  
Enables or disables turbo mode.

**C States**  
Enables or disables CPU power management. This allows the CPU to go into C states when it is not 100% utilized.

PCH-FW Configuration

This section is used to configure the firmware update options.

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Advanced

ME Firmware Version

12.0.22.1310

Configure Intel(R) Active Management Technology Parameters

ME Firmware Mode

Normal Mode

ME Firmware SKU

Corporate SKU

ME Firmware Status 1

0x90000255

ME Firmware Status 2

0x89108106

ME State

[Enabled]

Manageability Features State

[Enabled]

AMT BIOS Features

[Enabled]

▶ AMT Configuration

ME Unconfig on RTC Clear

[Enabled]

▶ Firmware Update Configuration

→←: Select Screen

↑↓: Select Item

Enter: Select

+/-: Change Opt.

F1: General Help

F2: Previous Values

F3: Optimized Defaults

F4: Save & Exit

ESC: Exit

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- ME Unconfig on RTC Clear**  
Enables or disables ME to unconfigure on RTC clear.





AMT Configuration



USB Provisioning of AMT

Enables or disables USB provisioning of AMT.

Secure Erase Configuration



Secure Erase mode

Configures the Secure Erase module behavior.

- Simulated      Performs SE flow without erasing SSD.
- Real            Erases SSD.

Force Secure Erase

Enables or disables the option to Force Secure Erase on next boot.



OEM Flags Settings

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Advanced

Hide Unconfigure ME Confirmation Prompt	[Disabled]	OEMFlag Bit 6: Hide Unconfigure ME confirmation prompt when attempting ME unconfiguration.
Unconfigure ME	[Disabled]	

→←: Select Screen  
↑↓: Select Item  
Enter: Select  
+/-: Change Opt.  
F1: General Help  
F2: Previous Values  
F3: Optimized Defaults  
F4: Save & Exit  
ESC: Exit

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Hide Unconfigure ME Confirmation Prompt

Enables or disables the option to hide unconfigure ME confirmation prompt when attempting ME unconfiguration.

Unconfigure ME

Enables or disables Unconfigure ME to reset the MEBx password to default.

Firmware Update Configuration

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Advanced

Me FW Image Re-Flash	[Disabled]	Enable/Disable Me FW Image Re-Flash function.
----------------------	------------	---

→←: Select Screen  
↑↓: Select Item  
Enter: Select  
+/-: Change Opt.  
F1: General Help  
F2: Previous Values  
F3: Optimized Defaults  
F4: Save & Exit  
ESC: Exit

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Me FW Image Re-Flash

Enables or disables ME firmware image re-flash function.





Trusted Computing

This section is used to configure Trusted Platform Module (TPM) settings.

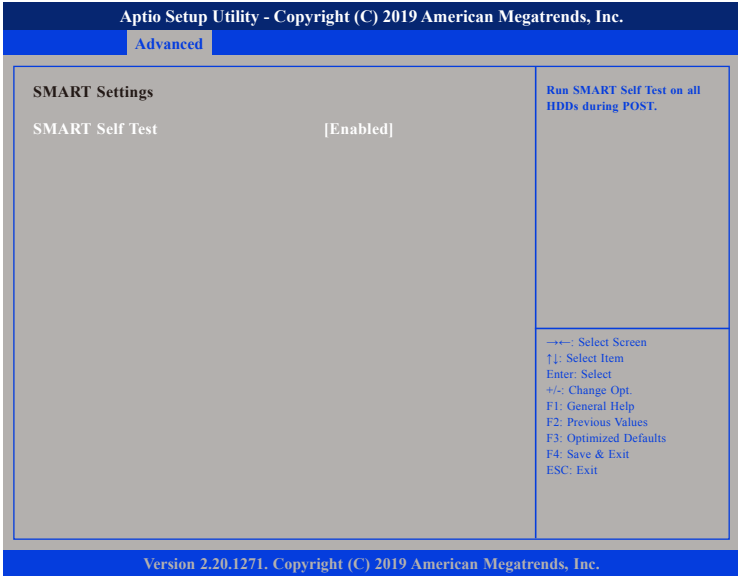


Security Device Support

Enables or disables BIOS support for security device. O.S will not show Security Device. TCG EFI protocol and INT1A interface will not be available.

SMART Settings

This section is used to configure the SMART feature for hard drives.



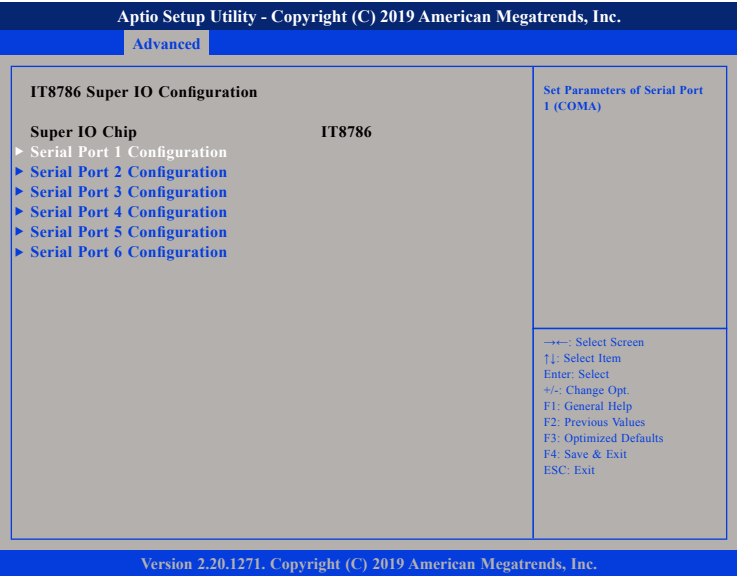
SMART Self Test

Enables or disables SMART self test on all hard drives during POST.



### IT8786 Super IO Configuration

This section is used to configure serial ports 1 to 6 of the super IO.



#### Super IO Chip

Displays the Super I/O chip used on the board.

### IT8528 Super IO Configuration

This section is used to configure serial ports 1 and 2 of the second super IO.



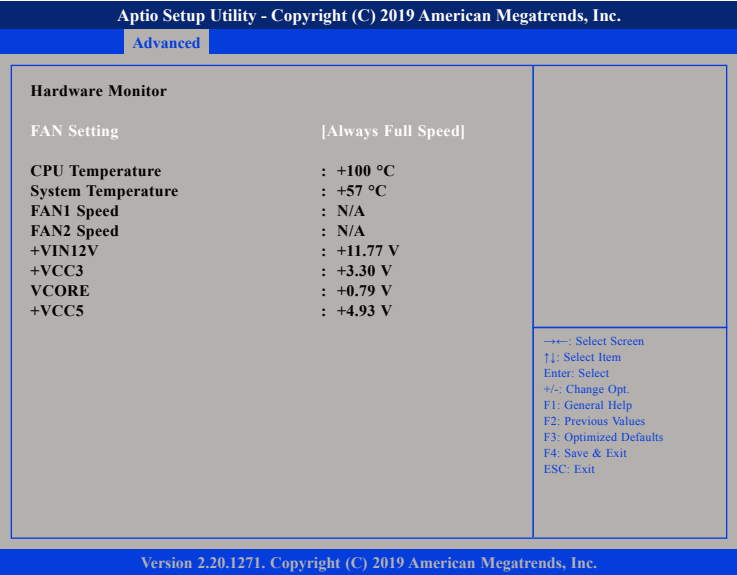
#### Super IO Chip

Displays the second Super I/O chip used on the board.



Hardware Monitor

This section is used to monitor hardware status such as temperature, fan speed and voltages.



FAN Setting

Configures the operating mode of the fan. The available options are Always Full Speed, Enable Smart Fan and Disable.

CPU Temperature

Detects and displays the current CPU temperature.

System Temperature

Detects and displays the current system temperature.

FAN1 and FAN2 Speed

Detects and displays FAN1 and FAN2 speed.

+VIN12V to +VCC5

Detects and displays the output voltages.

Serial Port Console Redirection

This section is used to configure the serial port that will be used for console redirection.



Console Redirection

Enables or disables console redirection.

USB Configuration

This section is used to configure the USB.



Legacy USB Support

- Enable Enables Legacy USB.
- Auto Disables support for Legacy when no USB devices are connected.
- Disable Keeps USB devices available only for EFI applications.

XHCI Hand-off

This is a workaround for OSs that does not support XHCI hand-off. The XHCI ownership change should be claimed by the XHCI driver respectively.

USB Mass Storage Driver Support

Enables or disables USB mass storage driver support.



**USB transfer time-out**

The time-out value for control, bulk, and Interrupt transfers.

**Device reset time-out**

Selects the USB mass storage device’s start unit command timeout.

**Device power-up delay**

Maximum time the value will take before it properly reports itself to the Host Controller. “Auto” uses default value: for a Root port it is 100 ms, for a Hub port the delay is taken from Hub descriptor.

**Network Stack Configuration**

This section is used to configure the network stack settings.



**Network Stack**

Enables or disables UEFI network stack.

**Ipv4 PXE Support**

Enables or disables IPv4 PXE support. If disabled, the IPv4 boot option will not be created.

**Ipv4 HTTP Support**

Enables or disables IPv4 HTTP support.





### **Ipv6 PXE Support**

Enables or disables IPv6 PXE support. If disabled, the IPv6 boot option will not be created.

### **Ipv6 HTTP Support**

Enables or disables IPv6 HTTP support.

### **IP6 Configuration Policy**

Configures the IP6 configuration policy.

### **PXE boot wait time**

Configures the wait time to press the ESC key to abort the PXE boot.

### **Media detect count**

Configures the number of times the media will be checked.





### Chipset

This section is used to configure the system based on the specific features of the chipset.



Setting incorrect field values may cause the system to malfunction.



#### LVDS Panel Type

Configures the LVDS panel resolution.

### System Agent (SA) Configuration



#### Graphics Configuration

Enters the graphics chip settings sub-menu.

#### PEG Port Configuration

Enters the PEG port settings sub-menu.



Graphics Configuration

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Chipset

Graphics Configuration

Primary Display

Internal Graphics

[Auto]

[Auto]

Select which of IGFX/PEG/PCI Graphics device should be Primary Display Or select SG for Switchable Gfx.

→←: Select Screen

↑↓: Select Item

Enter: Select

+/-: Change Opt.

F1: General Help

F2: Previous Values

F3: Optimized Defaults

F4: Save & Exit

ESC: Exit

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Primary Display

Select which of IGFX/PEG/PCI graphics device should be the primary display or select SG for switchable GFX.

Internal Graphics

Keep IGFX enabled based on the setup options.

PEG Port Configuration

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Chipset

PEG Port Configuration

PEG 0:1:0

Enable Root Port

Max Link Speed

Not Present

[Auto]

[Auto]

Enable or Disable the Root Port

→←: Select Screen

↑↓: Select Item

Enter: Select

+/-: Change Opt.

F1: General Help

F2: Previous Values

F3: Optimized Defaults

F4: Save & Exit

ESC: Exit

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Enable Root Port

Enables or disables the root port.

Max Link Speed

Configures the maximum link speed of the PEG device.



PCH-IO Configuration



PCH LAN Controller

Enables or disables onboard NIC.

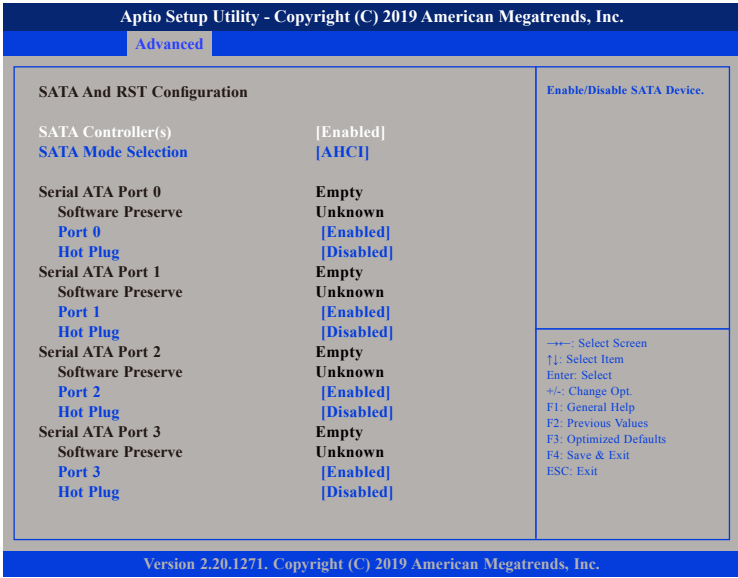
Wake on LAN Enable

Enables or disables integrated LAN to wake the system.

State After G3

Configures the state the system will enter when power is reapplied after a power failure (G3 state).

SATA And RST Configuration



SATA Controller(s)

Enables or disables the SATA controller.

SATA Mode Selection

Configures the SATA as AHCI mode.

Port 0 to Port 3

Enables or disables SATA port 0, port 1, port 2 or port 3.

Hot Plug

Enables or disables hot plugging feature on SATA port 0, port 1, port 2 or port 3.



## HD Audio Configuration



### HD Audio

Control detection of the HD audio device.

- |          |  |
|----------|--|
| Disabled | HD audio will be unconditionally disabled.               |
| Enabled  | HD audio will be unconditionally enabled.                |
| Auto     | HD audio will be enabled if present, disabled otherwise. |



Security

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MainAdvancedChipsetSecurityBootSave & Exit

Password Description

If ONLY the Administrator's password is set, then this only limits access to Setup and is only asked for when entering Setup.  
If ONLY the User's password is set, then this is a power on password and must be entered to boot or enter Setup. In Setup the User Will have Administrator rights.  
The password length must be in the following range:  
Minimum length3  
Maximum length20

Administrator Password  
User Password

Set Administrator Password

→←: Select Screen  
↑↓: Select Item  
Enter: Select  
+/-: Change Opt.  
F1: General Help  
F2: Previous Values  
F3: Optimized Defaults  
F4: Save & Exit  
ESC: Exit

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Administrator Password

Select this to reconfigure the administrator’s password.

User Password

Select this to reconfigure the user’s password.

Boot

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MainAdvancedChipsetSecurityBootSave & Exit

Boot Configuration

Setup Prompt Timeout1  
Bootup NumLock State[Off]  
Quiet Boot[Disabled]

Boot Option Priorities  
Boot Option #1[UEFI: Built-in EFI Shell]

Number of seconds to wait for setup activation key.  
65535(0xFFFF) means indefinite waiting.

→←: Select Screen  
↑↓: Select Item  
Enter: Select  
+/-: Change Opt.  
F1: General Help  
F2: Previous Values  
F3: Optimized Defaults  
F4: Save & Exit  
ESC: Exit

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Setup Prompt Timeout

This section configures the number of seconds to wait for the setup activation key.

Bootup NumLock State

This allows you to determine the default state of the numeric keypad. By default, the system boots up with NumLock on wherein the function of the numeric keypad is the number keys. When set to Off, the function of the numeric keypad is the arrow keys.

**Quiet Boot**

Enabled            Displays OEM logo instead of the POST messages.  
Disabled          Displays normal POST messages.

**Boot Option Priorities**

Adjust the boot sequence of the system. Boot Option #1 is the first boot device that the system will boot from, next will be #2 and so forth.

**Save & Exit**



**Save Changes and Reset**

To save the changes and reset, select this field then press <Enter>. A dialog box will appear. Confirm by selecting Yes.

**Discard Changes and Reset**

To exit the Setup utility and reset without saving the changes, select this field then press <Enter>. You may be prompted to confirm again before exiting.

**Restore Defaults**

To restore the BIOS to default settings, select this field then press <Enter>. A dialog box will appear. Confirm by selecting Yes.